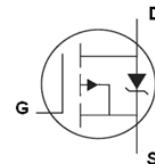
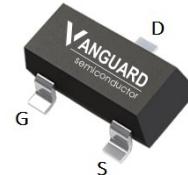


Features

- P-Channel
- Enhancement mode
- Fast Switching
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),max} @ V_{GS}=-10V$	52	mΩ
$R_{DS(on),max} @ V_{GS}=-4.5V$	62	mΩ
I_D	-3.4	A

SOT23



Part ID	Package Type	Marking	Tape and reel information
VS3540AC	SOT23	VS01	3000pcs/reel

Maximum ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-30	V	
I_s	Diode continuous forward current	$T_A = 25^\circ\text{C}$	-1.2	A
I_D	Continuous drain current@ $V_{GS}=-4.5V$	$T_A = 25^\circ\text{C}$	-3.4	A
		$T_A = 70^\circ\text{C}$	-2.7	A
I_{DM}	Pulse drain current tested ①	$T_A = 25^\circ\text{C}$	12	A
P_D	Maximum power dissipation	$T_A = 25^\circ\text{C}$	1	W
V_{GS}	Gate-Source voltage	± 12	V	
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	°C	

Thermal Characteristics

R_{eJL}	Thermal Resistance-Junction to Lead	80	°C/W
R_{eJA}	Thermal Resistance Junction-Ambient	125	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(T _j =25°C)	V _{DS} =-30V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T _j =125°C)	V _{DS} =-30V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.5	--	-1.2	V
R _{DS(ON)}	Drain-Source On-State Resistance②	V _{GS} =-10V, I _D =-4A	--	52	60	mΩ
		V _{GS} =-4.5V, I _D =-3A	--	62	70	mΩ
		V _{GS} =-2.5V, I _D =-2A	--	81	105	mΩ
Dynamic Electrical Characteristics @ T_j= 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	--	805	--	pF
C _{oss}	Output Capacitance		--	60	--	pF
C _{rss}	Reverse Transfer Capacitance		--	50	--	pF
R _g	Gate Resistance	f=1MHz	--	10	--	Ω
Q _q	Total Gate Charge	V _{DS} =-15V, I _D =-4A, V _{GS} =-4.5V	--	10	--	nC
Q _{qs}	Gate-Source Charge		--	2.3	--	nC
Q _{qd}	Gate-Drain Charge		--	4.2	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =-15 V, I _D =-4A, R _G =3Ω, V _{GS} =-4.5V	--	4	--	nS
t _r	Turn-on Rise Time		--	4	--	nS
t _{d(off)}	Turn-Off Delay Time		--	28	--	nS
t _f	Turn-Off Fall Time		--	4.6	--	nS
Source- Drain Diode Characteristics@ T_j= 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =-3A, V _{GS} =0V	--	-0.85	-1.2	V
t _{rr}	Reverse Recovery Time	T _j =25°C, I _{sd} =-3A, V _{GS} =0V di/dt=-100A/μs	--	12	--	nS
Q _{rr}	Reverse Recovery Charge			3.6		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width ≤ 300μs; duty cycle≤ 2%.



Typical Characteristics

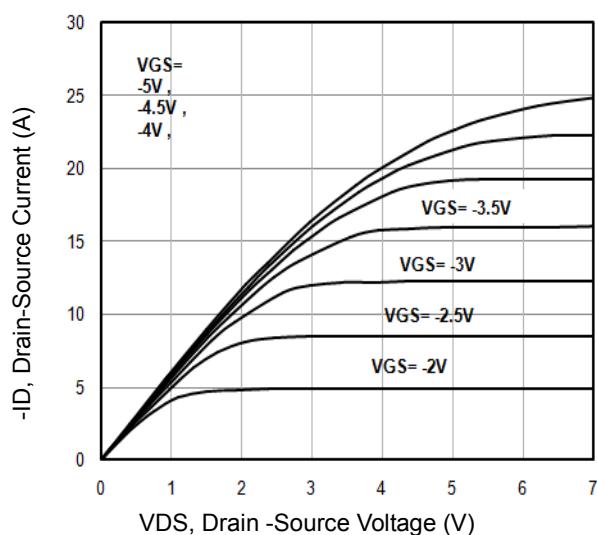


Fig1. Typical Output Characteristics

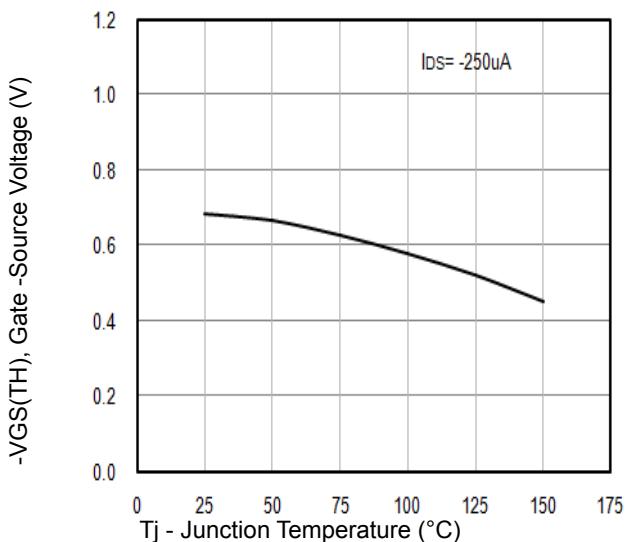


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

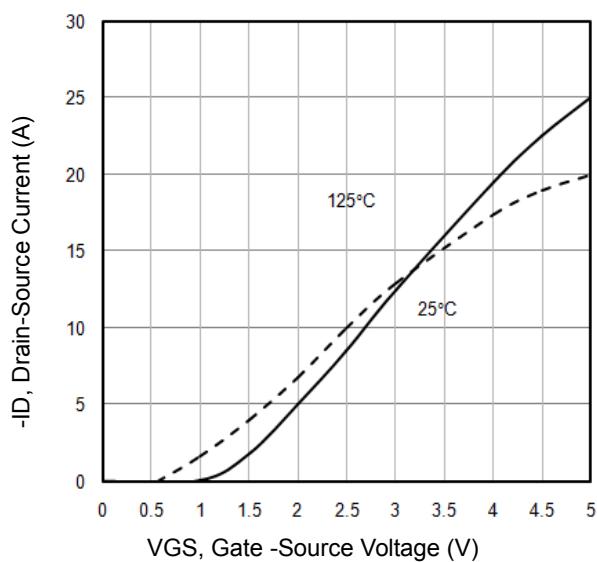


Fig3. Typical Transfer Characteristics

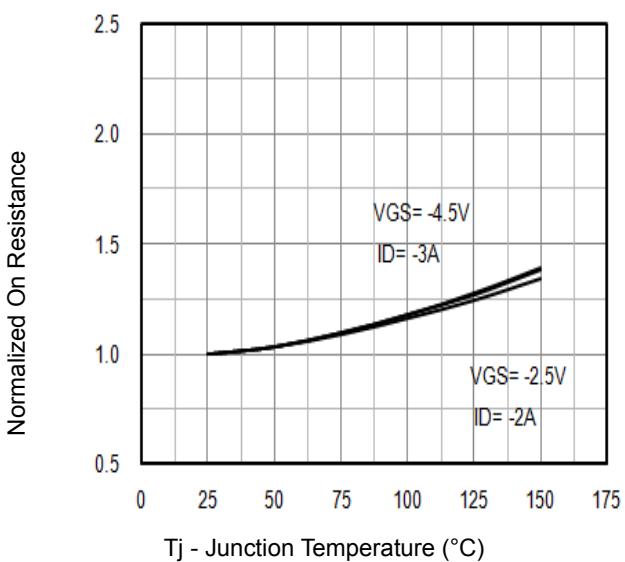


Fig4. Normalized On-Resistance Vs. T_j

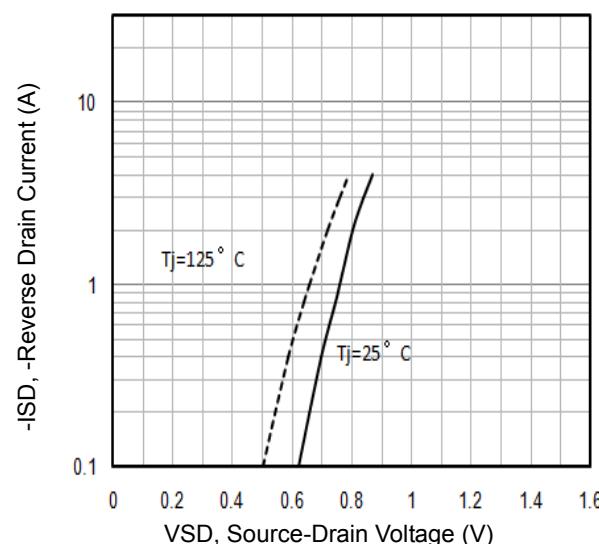


Fig5. Typical Source-Drain Diode Forward Voltage

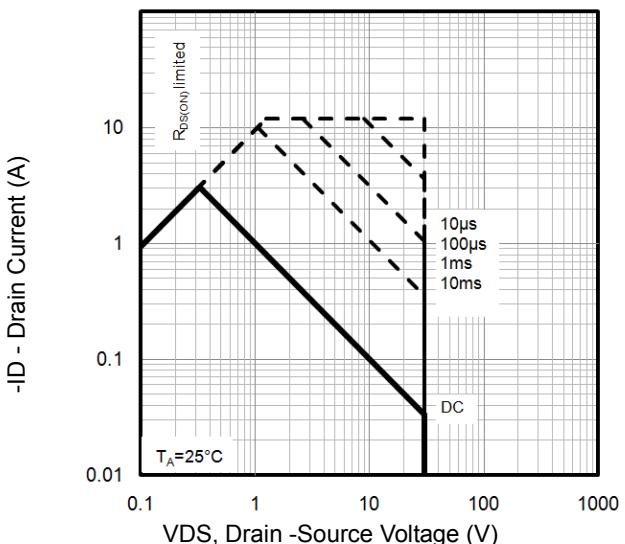


Fig6. Maximum Safe Operating Area



Typical Characteristics

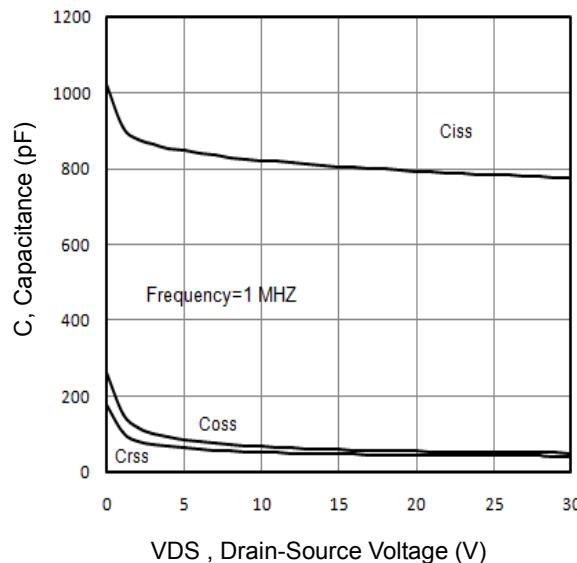


Fig7. Typical Capacitance Vs.Drain-Source Voltage

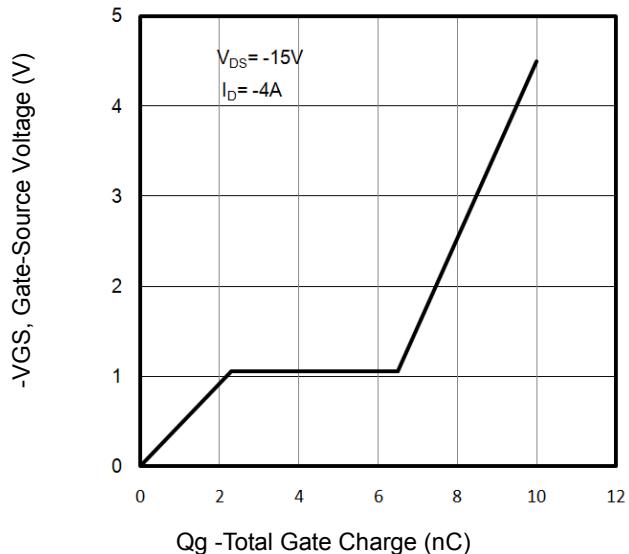


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

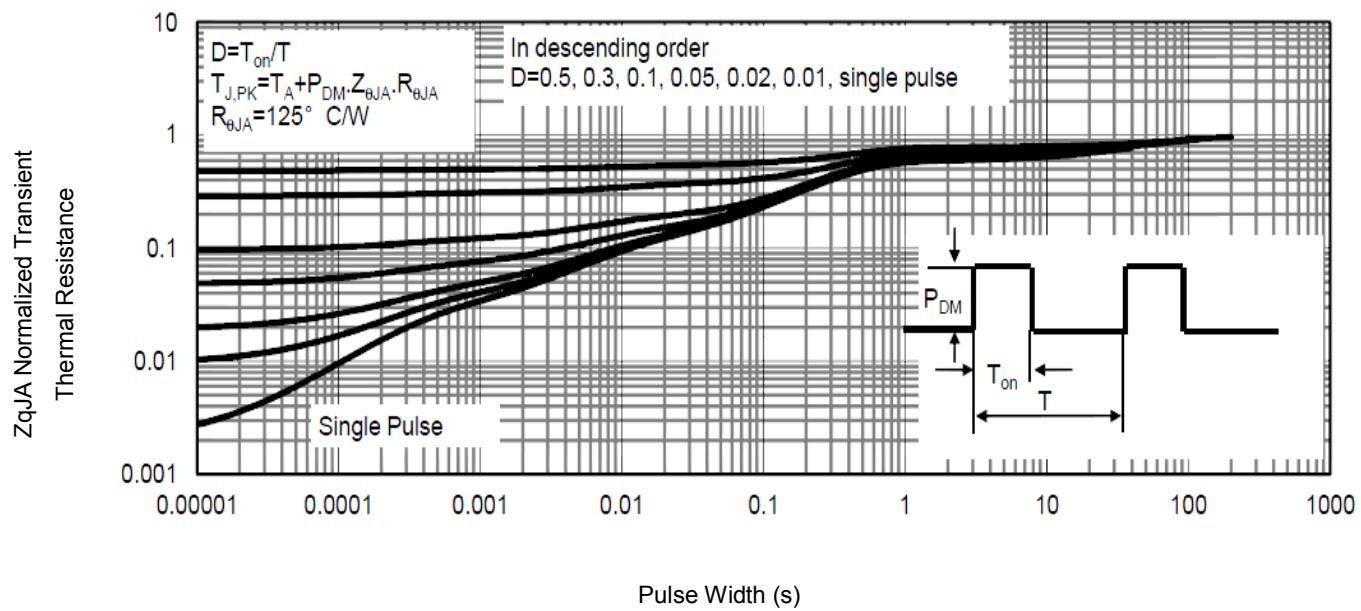


Fig9. Normalized Maximum Transient Thermal Impedance

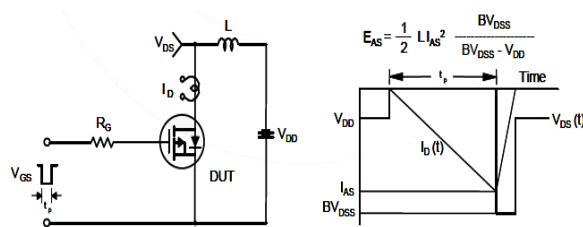


Fig10. Unclamped Inductive Test Circuit and waveforms

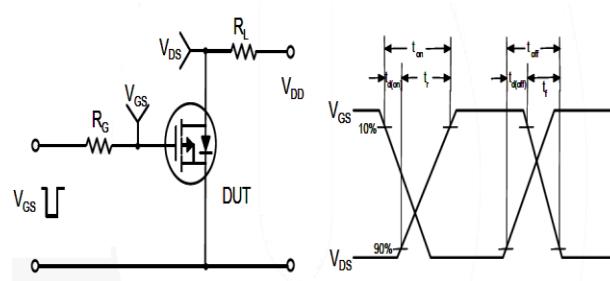
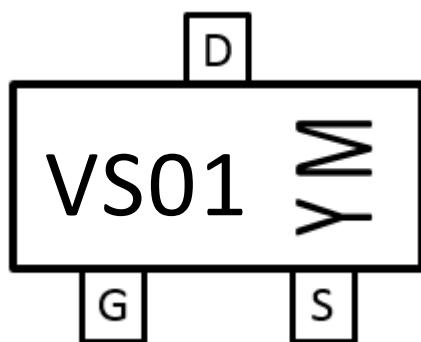


Fig11. Switching Time Test Circuit and waveforms

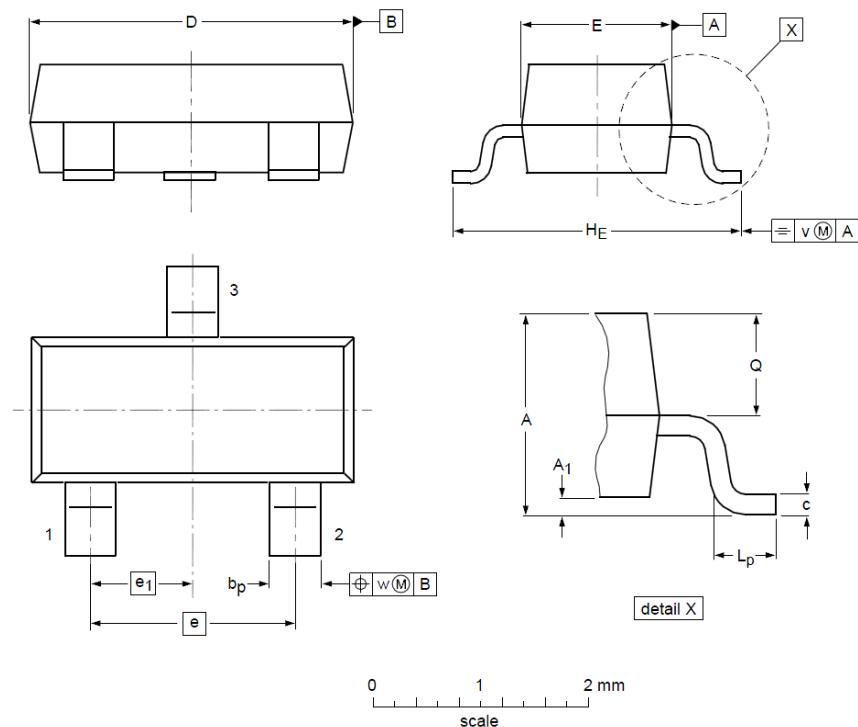
Marking Information



VS01: Part Number

YM: Date Code, Y means assembly year, M means assembly month

SOT23 Package Outline Data



Label	DIMENSIONS (unit: mm)		
	Min	Typ	Max
A	0.90	1.03	1.10
A₁	0.01	0.05	0.10
b_p	0.38	0.42	0.48
c	0.09	0.13	0.15
D	2.80	2.92	3.00
E	1.20	1.33	1.40
e	--	1.90	--
e₁	--	0.95	--
H_E	2.10	2.40	2.50
L_p	0.40	0.50	0.60
Q	0.45	0.49	0.55
v	--	0.20	--
w	--	0.10	--

Notes:

- Follow JEDEC TO-236, variation AB.
- Dimension "D" does NOT include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.25mm per side.
- Dimension "E" does NOT include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25mm per side.

Customer Service

Sales and Service:

sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com